

Title (en)
ELECTRONIC COMPONENT

Title (de)
ELEKTRONISCHES BAUELEMENT

Title (fr)
COMPOSANT ELECTRONIQUE

Publication
EP 0954879 A1 19991110 (DE)

Application
EP 97908115 A 19970122

Priority
DE 9700105 W 19970122

Abstract (en)
[origin: US6870245B1] The invention relates to an electronic component having an integrated circuit being packaged in a housing. The electronic component is adhesively bonded to an island of a leadframe, the island being designed to accommodate the integrated circuit and being dimensionally adapted to the base surface of the integrated circuit in order to minimize and prevent housing deformations.

IPC 1-7
H01L 23/495; **H01L 23/31**

IPC 8 full level
H01L 23/31 (2006.01); **H01L 23/495** (2006.01)

CPC (source: EP US)
H01L 23/3107 (2013.01 - EP US); **H01L 23/49503** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2924/10253** (2013.01 - EP US)

Citation (search report)
See references of WO 9832172A1

Designated contracting state (EPC)
DE

DOCDB simple family (publication)
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DOCDB simple family (application)
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